2SJ471

Silicon P Channel DV–L MOS FET High Speed Power Switching

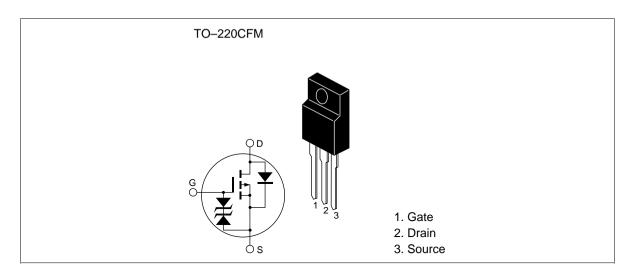
HITACHI

ADE-208-540

Features

- Low on-resistance $R_{DS(on)} = 25 \text{ m}\Omega \text{ typ.}$
- 4V gate drive devices.
- · High speed switching

Outline





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Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{ exttt{DSS}}$	-30	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	-30	A
Drain peak current	Note1	-120	A
Body to drain diode reverse drain current	I _{DR}	-30	A
Channel dissipation	Pch Note2	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

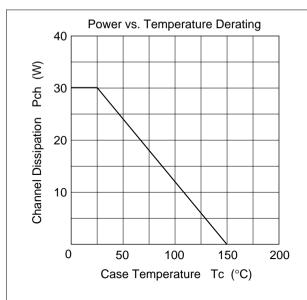
2. Value at Tc = 25°C

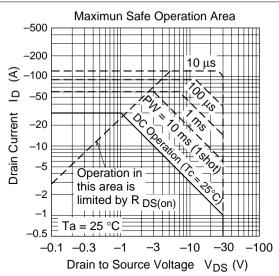
Electrical Characteristics ($Ta = 25^{\circ}C$)

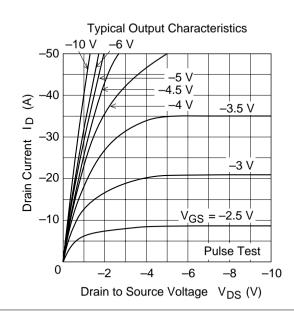
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-30	_	_	V	$I_{D} = -10 \text{mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \mu A, \ V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	-10	μА	$V_{DS} = -30 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16V, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	_	-2.0	V	$I_{D} = -1 \text{mA}, V_{DS} = -10 \text{V}$
Static drain to source on state	R _{DS(on)}	_	25	35	mΩ	$I_{\rm D} = -15 A, V_{\rm GS} = -10 V^{\rm Note3}$
resistance	R _{DS(on)}	_	40	60	$m\Omega$	$I_{\rm D} = -15 A, V_{\rm GS} = -4 V^{\rm Note3}$
Forward transfer admittance	y _{fs}	12	20	_	S	$I_{\rm D} = -15 A, V_{\rm DS} = -10 V^{\rm Note3}$
Input capacitance	Ciss	_	1700	_	pF	V _{DS} = -10V
Output capacitance	Coss	_	950	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	260	_	pF	f = 1MHz
Turn-on delay time	t _{d(on)}	_	20	_	ns	$V_{GS} = -10V, I_{D} = -15A$
Rise time	t _r	_	290	_	ns	$R_L = 0.67\Omega$
Turn-off delay time	t _{d(off)}	_	170	_	ns	
Fall time	t _f	_	130	_	ns	
Body to drain diode forward voltage	V_{DF}	_	-1.1	_	V	$I_F = -30A, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	70	_	ns	$I_F = -30A, V_{GS} = 0$ diF/ dt = $50A/\mu s$

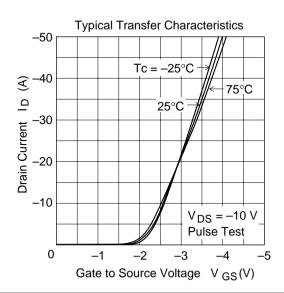
Note: 3. Pulse test

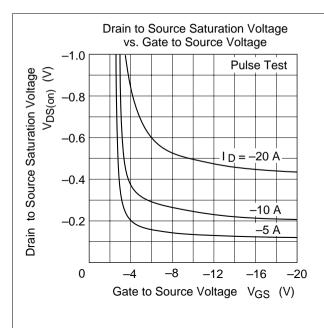
Main Characteristics

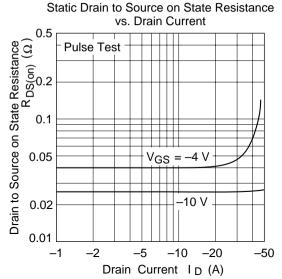


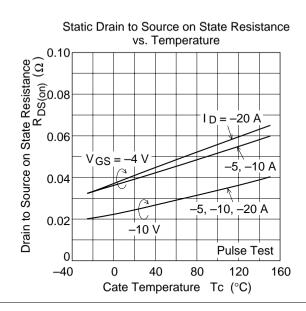


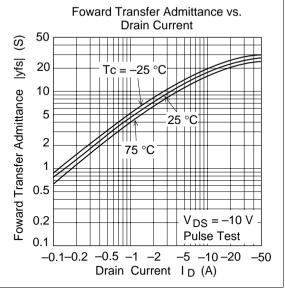


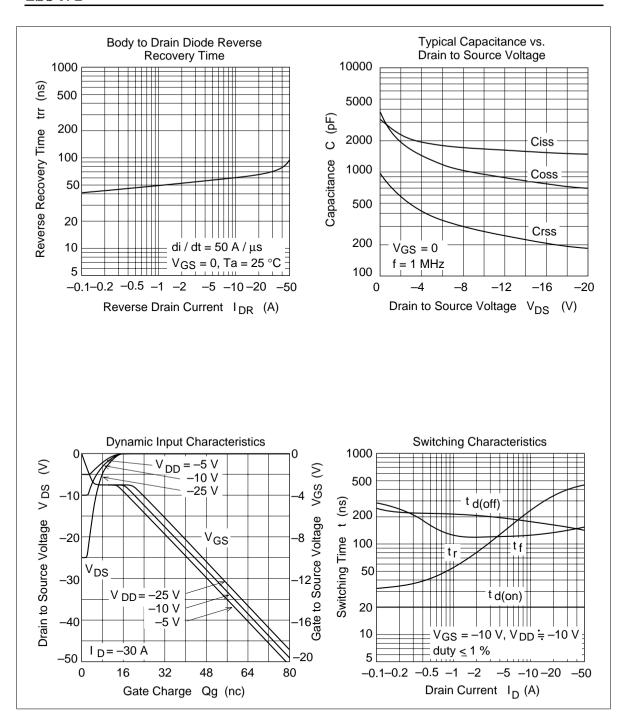


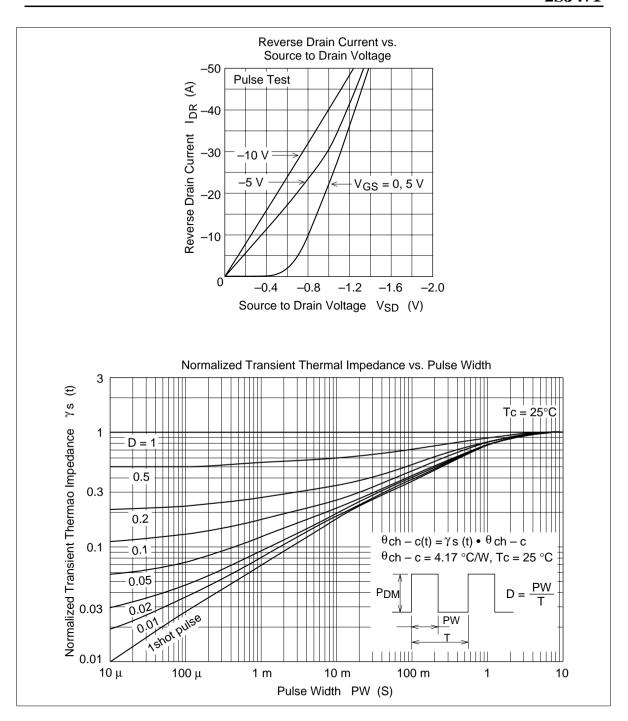




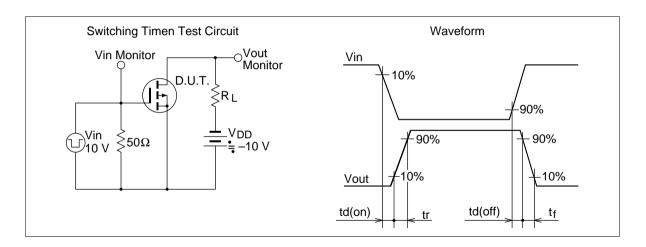






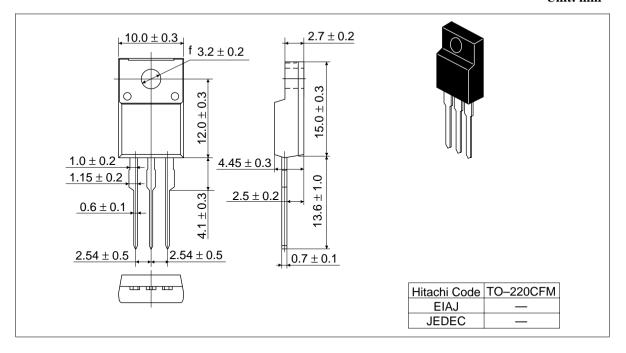


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Package Dimensions

Unit: mm



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